

BB02-CZ

CUSTOMER PRODUCT SPECIFICATION SHEET



BB02-CZ :- 1.27mm x 1.27mm (0.05" x 0.05") SOCKET, RIGHT ANGLE, THROUGH HOLE, DUAL ROW - 06 TO 80 CONTACTS

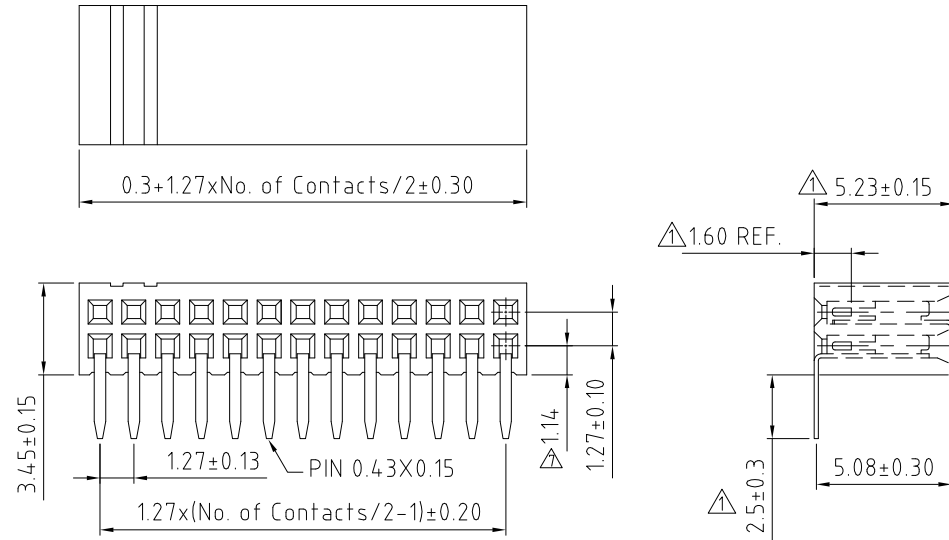
SPECIFICATIONS

CURRENT RATING	1 AMPS
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	AC 500 V
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0
	STANDARD : LCP+30% G/F
PLATING	GOLD OR TIN OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC
	WAVE: 250°C FOR 5-10 SEC
	MANUAL SOLDER: 380°C FOR 3-5SEC

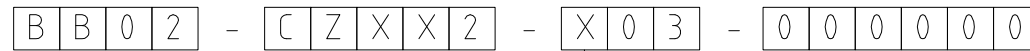
NOTES:

1. PACKED IN TUBE.
2. RECOMMENDED MATING PIN LENGTH: 3.5MM. Δ

MATES WITH: BB02-BC BB02-NE
 BB02-BD
 BB02-BK
 BB02-BP
 BB02-BS



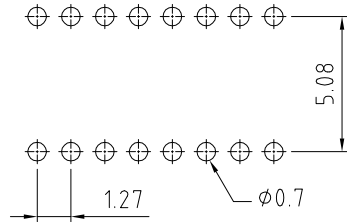
HOW TO ORDER



NO. OF CONTACTS:
06 TO 80

CONTACT PLATING OPTIONS:

- K = GOLD FLASH (STANDARD)
- A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- T = BRIGHT TIN
- M = MATT TIN



RECOMMENDED PC BOARD SMD LAYOUT
(TOLERANCE: ± 0.05)

REV.	DATE & DRN.
10	18/08/06 - NYW RELEASE
11	04/06/07 - NYW FOR LAYOUT.
12	ADD PIN LENGTH.
13	ADD CONTACT DIM.
14	REMOVE SELECTIVE GOLD CONTACT PLATING.
15	21/05/08 - CHC PLATING MODIFICATION.
16	29/12/08 - CHC DRAWING MODIFICATION
17	22/12/09 - NYW CHANGE INSULATOR TO LCP.
18	25/08/11 - NYW ADD SECOND GROOVE.
19	23/07/14 - NYW AMEND DIMENSION.

Scale:	5:1	THIRD ANGLE	Unstated Tolerances:	Material
Drawn:	CHC		X. ± 0.30	SEE NOTE
App'd:	XXXX	Title:	X ± 0.25	NOT TO SCALE
Date:	23 OCT. '14	Revision:	.XX ± 0.15	Unit: mm
			.XXX ± 0.10	

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Type:	BB02-CZ
Drawing Number:	BB02-CZ
Sheet	1 of 1
Drawing	© E and O E